

Fraunhofer Institute for Telecommunications



SCUBE-ICT – Emerging opportunities under FP7-ICT Call 5

Minsk, 25.-26.06.2009

Dr. Sven-Hendrik Voß

**Einsteinufer 37
10587 Berlin
Germany**

**Phone: +49 30 310 02 – 0
Fax: +49 30 310 02 – 213
eMail: info@hhi.fraunhofer.de
Internet: <http://www.hhi.fraunhofer.de>**

Organisation Profile



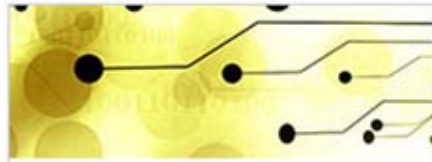
Photonic Networks & Systems



Photonic Components



Image Processing



Interactive Media - Human Factors



Broadband Mobile Communication Networks



Fiber Optical Sensor Systems

Image Processing Department

Head Dr. Ralf Schaefer

Image Communication

Dr. T. Wiegand

Computer Vision & Graphics

Dr. P. Eisert

Immersive Media & 3D Video

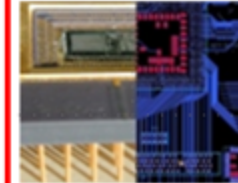
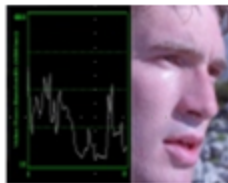
P. Kauff

Hardware Architectures & PCB Design

Dr. S. Voss

Embedded Systems

Dr. B. Stabernack

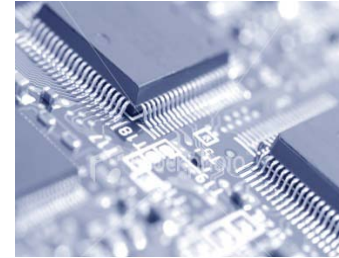


Leading Edge Technology Solutions

- Engineering design expertise in the area of FPGA design, high-speed PCB design and complete system design
- Competence and special know-how:
 - High-speed PCB and system design (specialized in RF layout techniques, applications for beyond 100 Gbps)
 - FPGA implementations and ASIC designs
 - Digital signal processing in hardware (for digital video, image processing, audio, network environments, etc.)
 - Protocol stacks development (IP Cores)
 - Software application development
- Design and research capabilities are focused towards innovative technologies and high-end applications

Research Fields and Interests

- Field-programmable logic devices
- Electronic and photonic high-speed communications and technology (beyond 100 Gbps)
- Analog and digital VLSI circuits
- High-speed Interconnects (analysis of parasitic effects, nano-technology, circuit interconnects, copper and optical interconnects)
- Systems and algorithms for (image) data processing
- Parallel signal processing and adaptive computation
- Data compression (lossy / lossless) and digital filters for audio / video applications
- Advanced high-speed compound semiconductor devices, processes and circuits for the telecommunications industry of the future



Curriculum Vitae: Dr. Sven-Hendrik Voß

- Senior scientist / project manager / group leader at the FhG-HHI
- Lecturer for teaching engineering classes at University of Applied Sciences (Beuth Hochschule für Technik Berlin)
- Received Dipl.-Ing. degree in Electrical Engineering from Berlin University of Technology in 2003 and the Dr.-Ing. degree in 2008, respectively
- Research interests: image processing, hardware and embedded systems, high-speed data processing, analog and digital RF circuit design, high-speed communications systems, data compression

Collaboration Requests

- Explore partnership opportunities via industry and research consortia to conduct conjoint research projects
- Implement initiatives to increase cross-faculty research
- Build new links with industry to promote wider opportunities for
 - Collaborative research
 - Supply of new key technologies and / or products
 - Integration of different architectures, systems, standards for future data communication / processing

Appendix

Folie 7

29.06.2009

© Fraunhofer HHI

R&D in the HWA&PCB Group

- Circuits, Architectures and Design
- IC component design (algorithmic level → physical implement. level)
- VHDL implementations and IP Core design
- Multi-platform support: ASICs, FPGA, Microprocessors
- Technology and Devices
- Feasibility studies
- Consulting
- Concept engineering
- Systems and Applications
- System design (Hardware, Firmware, Software)
- PCB design (schematics and layout) and simulation (circuit and EMI)
- Prototype development

Our Strengths...

- In comparison to other Information Technology Institutes and /or the Industry:

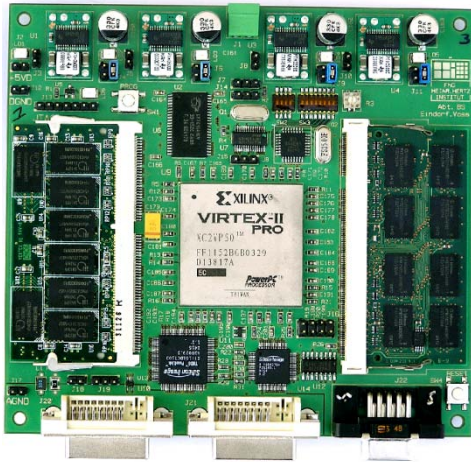
Thorough combination of...

- Algorithm design
- Circuit design
- Circuit and board simulation
- Layout design for high frequency applications
- Optical signal transmission (integration)
- FPGA and ASIC Design
- RF and Microwave test and measurement

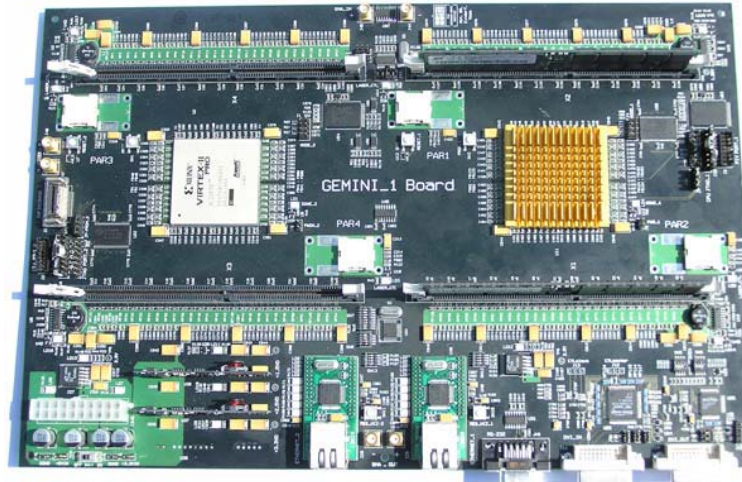
Our „Customers“ and Cooperation Partners...

- System Houses (Siemens, Wincor Nixdorf, ...)
- Communications Industry (Alcatel, Keymile, ...)
- Semiconductor Industry (Fujitsu, ...)
- Automotive Industry (Bosch, Hella-Aglaia, ...)
- Medicine Electronics (Elfi-Tech Ltd., ...)
- Production Equipment (IMS Nano, Vistec, ...)
- Industrial Electronics
- Research Institutions
- many SMEs

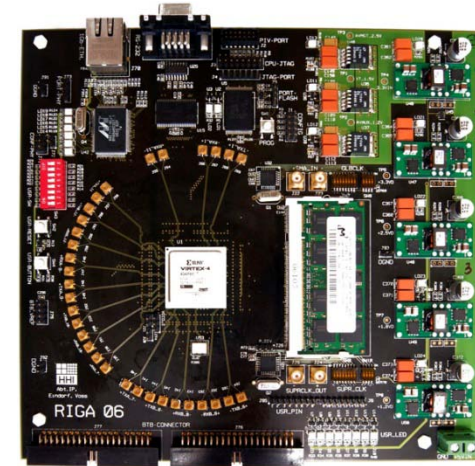
Recent Board and ASIC developments – 1/2



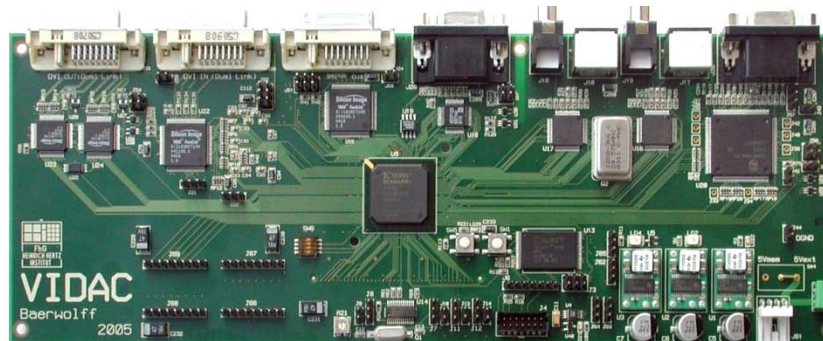
ML2 Board
(Virtex-II Pro XC2VP50 FPGA)



GEMINI Board (Virtex-II Pro XC2VP70 FPGA)



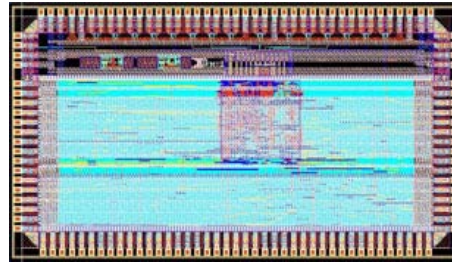
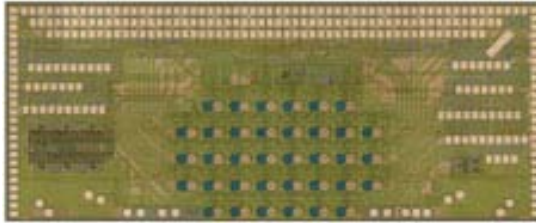
RIGA06 Board (Virtex-4 FX60 FPGA)



VIDAC (Video and Audio Interface) Board
(Spartan XC3S1000 FPGA)

Recent Board and ASIC developments – 2/2

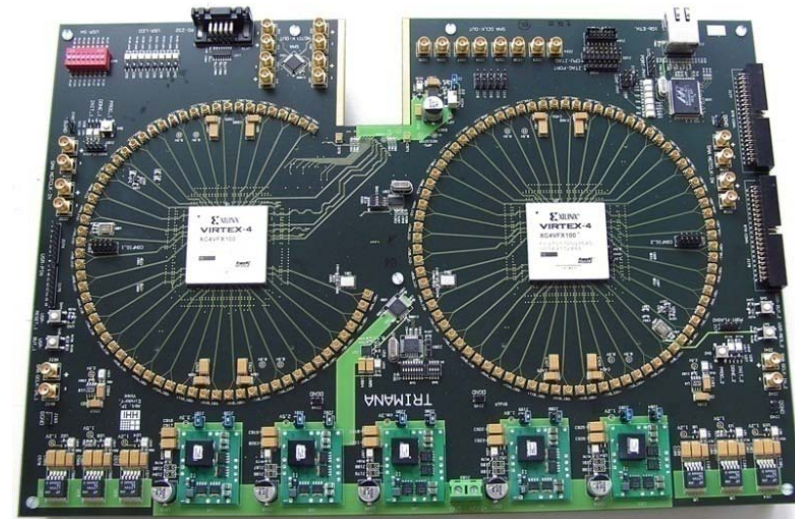
Parallel Optical Receiver in
0.6 μ m BiCMOS Technology
(36 parallel Ch. @ 2 Gbps,
600 mW power consumption)



Demux and Data Processor in
0.18 μ m CMOS Technology
(8 parallel Ch. @ 2 Gbps,
250 mW power consumption)



OptICA Board: OptRx w/
VCSEL on ceramics & FR4



TRIMANA Board (Virtex-4 FX100)